ABSTRACT OF THE DISCLOSURE

TAPE CARRIER FOR BGA AND SEMICONDUCTOR DEVICE USING THE SAME

A tape carrier is constituted comprising land 12 for solder ball, formed in a predetermined pattern on insulating film 7 having device hole 10 formed in the middle, leads 9 to be connected to a semiconductor chip, plating power-feeding lead 13 having one end connected to lead 9 and formed on insulating film 7, and easily-broken part 19 provided in the middle of the power-feeding leads. A semiconductor device is constituted wherein tape carrier 2 is provided with plating power-feeding lead 13 formed on insulating film 7, one end of which is drawn out of insulating film 7, the other end being connected to leads 9, and plating power-feeding lead 13 is disconnected from the leads when semiconductor chip 1 is installed. Thus, a tape carrier for BGA which is manufactured easily, capable of achieving higher density of wiring in the wiring pattern, improved in water-resistance and reliability, and a semiconductor device using the same are provided.

(Figure 1)